

WHAT IS CLAIMED IS:

Sub B2  
1. A process for producing a cured film having the memory of a specified shape, which process comprises shaping a resin composition by either applying it onto a shaped part or placing it between films, curing said resin composition with electron beams, and removing the cured composition from the shaped part or films, said resin composition comprising:

- (a) an oligomer compound that has at least one acryloyl or methacryloyl group in the molecule and that has a glass transition temperature,  $T_g$ , of lower than  $50^{\circ}\text{C}$  after polymerization; and
- (b) a low-molecular weight compound that has in its molecule one reactive double bond capable of polymerization with the oligomer compound (a) and that has a glass transition temperature,  $T_g$ , higher than at least  $90^{\circ}\text{C}$  after polymerization; or
- (b') a mixture of two or more low-molecular weight compounds that have in their molecule one reactive double bond capable of copolymerization with the oligomer compound
- (a) and that have a glass transition temperature,  $T_g$ , higher than  $90^{\circ}\text{C}$  after polymerization.

2. A process for producing a cured film having the memory of a specified shape, which process comprises shaping a resin composition by either applying it onto a shaped part or placing it between films, curing said resin composition with electron beams, and removing the cured composition from the shaped part or films, said resin composition comprising:

- (a) an oligomer compound that has at least one acryloyl or methacryloyl group in the molecule and that has a glass transition temperature,  $T_g$ , lower than  $50^{\circ}\text{C}$  after polymerization;
- (b) a simple urethane adduct of hydroxyethyl acrylate or hydroxyethyl methacrylate and a diisocyanate; and
- (c) an optional low-molecular weight compound that has in its molecule at least one double bond capable of copolymerization with the oligomer compound (a).

Add B3